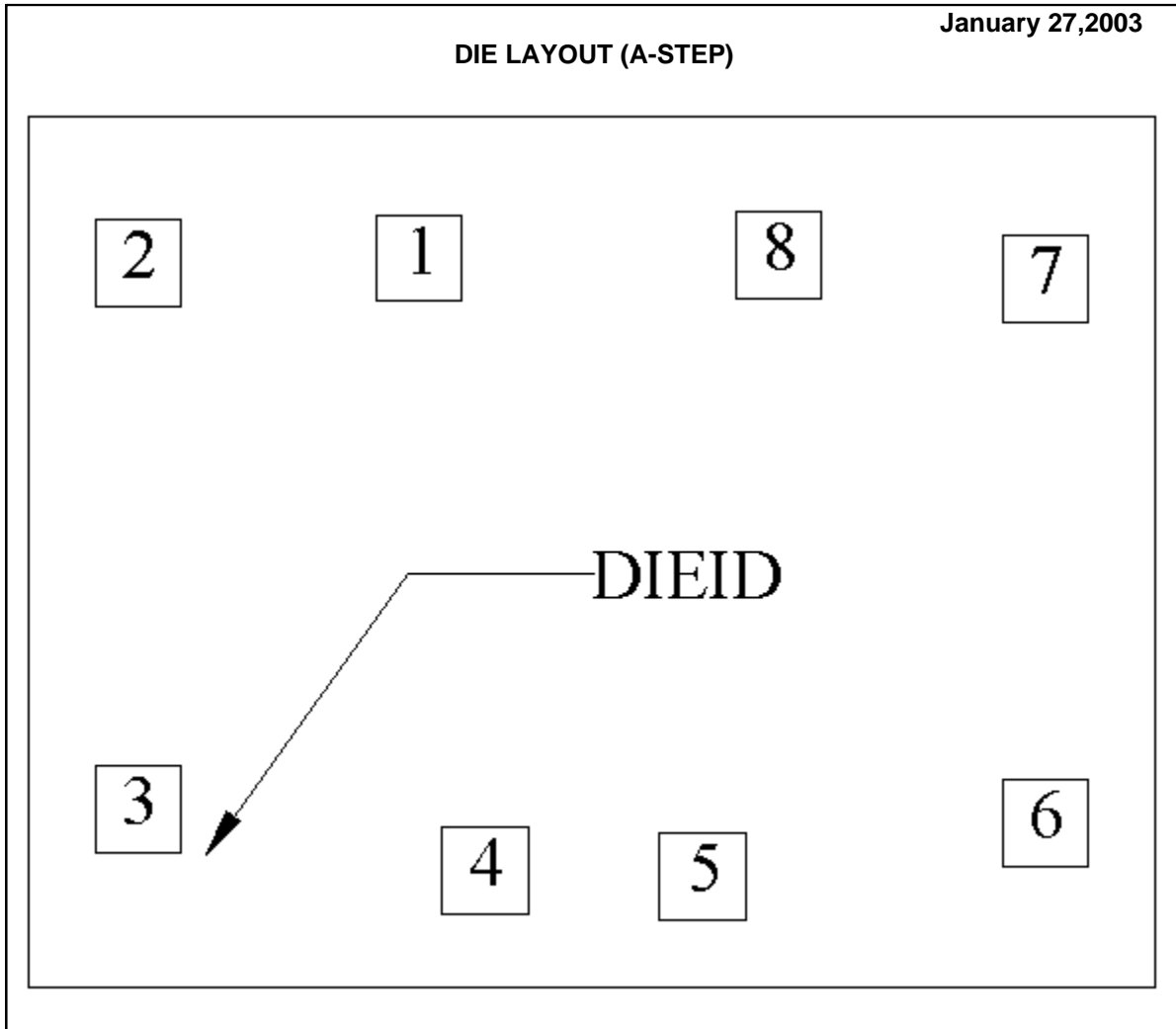


LMH6646 MDC MWC
2.7V, 650 μ A, 55MHZ, DUAL RAIL-TO-RAIL INPUT AND OUTPUT AMPLIFIER



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMH6646A	Bond Pad Opening Size (min)	90 μ m x 90 μ m
Die Step	A	Bond Pad Metalization	0.5% COPPER_BAL. ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1179 μ m x 909 μ m 46.4mils x 35.8mils	Back Side Connection	Floating
Thickness	216 μ m Nominal		
Min Pitch	228 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in μ m) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y CORRINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
OUTPUT A	1	-181	306	90	x	90
INPUT A -	2	-474	301	90	x	90
INPUT A+	3	-474	-269	90	x	90
V -	4	-112	-333	90	x	90
INPUT B +	5	116	-339	90	x	90
INPUT B -	6	474	-284	90	x	90
OUTPUT B	7	474	285	90	x	90
V+	8	195	310	90	x	90

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